NATIONAL AERONAUTICS AND SPACE ADMINISTRATION
WASHINGTON, D.C. 20546

REPLY TO
ATTN OF:

March 27, 1971

TO: USI/Scientific & Technical Information Division
Attention: Miss Winnie M. Morgan

FROM: GP/Office of Assistant General
Counsel for Patent Matters

SUBJECT: Announcement of NASA-Owned
U.S. Patents in STAR

In accordance with the procedures contained in the Code GP to Code USI memorandum on this subject, dated June 8, 1970, the attached NASA-owned U.S. patent is being forwarded for abstracting and announcement in NASA STAR.

The following information is provided:

U.S. Patent No. : 3,357,093

Corporate Source : California Institute of Technology

Supplementary
Corporate Source : Jet Propulsion Laboratory

NASA Patent Case No.: XNP-03459

Please note that this patent covers an invention made by an employee of a NASA contractor. Pursuant to Section 305(a) of the National Aeronautics and Space Act, the name of the Administrator of NASA appears on the first page of the patent; however, the name of the actual inventor (author) appears at the heading of Column No. 1 of the Specification, following the words ". . . with respect to an invention of. . . ."

Gayle Parker

Enclosure:
Copy of Patent

United States Patent Office

3,357,093

Patented Dec. 12, 1967

3,357,093

SOLDERING WITH SOLDER FLUX WHICH LEAVES CORROSION-RESISTANT COATING

James E. Webb, Administrator of the National Aeronautics and Space Administration, with respect to an invention of Albert J. Bauman, Sierra Madre, Calif.

No Drawing. Filed May 21, 1965, Ser. No. 457,879

12 Claims. (Cl. 29—495)

ABSTRACT OF THE DISCLOSURE

The soldering of metals employing hydrazine monoperfluoro alkanoate as a fluxing agent in order to leave a soldered area having a corrosion resistant inert polymeric coating.

The invention described herein was made in the performance of work under a NASA contract and is subject to the provisions of Section 305 of the National Aeronautics and Space Act of 1958, Public Law 85–568 (72 Stat. 435; 42 USC 2457).

This invention relates generally to a new solder flux useful in the joining of metals such as copper.

It is important in many applications that a soldered joint should not be the source of corrosion or be subject to corrosion. The avoidance of corrosion is particularly important where sterility must be maintained, such as in space capsules. However, the numerous soldered joints in the electronic components in a space craft provide a possible source of unwanted corrosion. Various soldering fluxes have been developed which leave little or no corrosive resinous residue. Typical of such commercially available fluxes are those based on the inorganic acid salts of hydrazine. While these fluxes do not generate any corrosive residues, they are themselves subject to attack by foreign material.

Briefly, the present invention involves soldering in the presence of a novel fluxing agent which is hydrazine monoperfluoro alkanoate. More particularly, the invention comprehends the method of soldering a metal in the presence of an effective fluxing amount of hydrazine monoperfluoro alkanoate, to leave a soldered area containing a corrosion resistant inert polymeric coating.

It has been found that the polymer coating provided by the fluxes of the present invention tenaciously adheres to the soldered surface. In addition, the polymeric material has been found to be resistant to the effect of strong chemicals, acids, and the like. While not bound by any theory it is believed that the polymeric material present is generally in the form of an oriented monolayer of a fluorocarbon polymer.

In general, the novel hydrazine monoperfluoro alkanoates used as the flux in the present invention, are long chain materials containing at least four and up to about twenty carbon atoms. More preferably, the materials contain from about seven to about sixteen carbon atoms. Typical novel fluxing agents of this invention include hydrazine monoperfluoro hexanoate, hydrazine monoperfluoro decanoate, hydrazine monoperfluoro dodecanoate, hydrazine monoperfluoro tridecanoate, hydrazine monoperfluoro hexadecanoate, and hydrazine monoperfluoro eicosanoate.

The fluxing materials of this invention are particularly adapted for use with lead-tin solder, wherein the ingredients are present in a 60/40 weight ratio, respectively. However, as will be apparent to those skilled in the art, the fluxing materials have applicability to other soldering materials. Some of the other solder useful with the fluxes of this invention are as follows: 30/70 tin-lead, 30/70 tin-zinc, 60/40 zinc-cadmium, 85/15 tin-zinc, 30/70 tin-zinc containing a small amount of antimony, and 30/70 tin-zinc containing a small amount of copper.

The novel fluxing materials of this invention may be prepared by neutralizing an aqueous solution of a perfluoro alkanoic acid with hydrazine, most conveniently at room temperature, in accordance with the following general reaction equation:

$$CF_3-(CF_2)_n-COOH + NH_2-NH_2 \longrightarrow CF_3-(CF_2)_n-COOH-NH_2-NH_2$$

wherein n is an integer.

The following example illustrates the invention. In the example, the parts and percentages are by weight unless otherwise indicated.

Example

Hydrazine monoperfluoro octanoate was prepared by adding neat hydrazine to an aqueous solution of perfluoro octanoic acid (sold under the designation FC–26 by Minnesota Mining and Manufacturing Company) in the presence of methyl red indicator to a pH 7. The salt, which was a white wax, was recovered by evaporation of the water. The hydrazine monoperfluoro octanoate was then applied to a copper joint and heated; then molten lead/tin (60/40) was applied and the soldering completed. The hydrazine monoperfluoro octanoate proved to be an excellent flux, giving a zero contact angle, and providing a strong joint. The finished joint was found to be coated with a thin adherent layer of a fluorocarbon polymer which was corrosion resistant, and impervious to strong acid. When the hydrazine monoperfluoro octanoate was heated alone on a copper sheet to its melting point, the treated surface subsequently resisted corrosion by hydrogen chloride vapor.

When the foregoing example was repeated using hydrazine monoperfluoro myristate, a corrosion-resistant strong soldered joint was obtained.

While the fluxing agent of this invention is particularly adapted to the soldering of copper, it will be readily appreciated by those skilled in the art that my invention has application of a wide variety of metals and metal alloys.

Having fully described the invention, it is intended that it be limited solely by the lawful scope of the appended claims.

I claim:

1. A method of soldering metal in which a corrosion-resistant coating is provided, which comprises applying molten solder to the metal in the presence of a fluxing agent which is a hydrazine monoperfluoro alkanoate.

2. A method of soldering metal in which a corrosion-resistant coating is provided, which comprises applying molten solder to the metal in the presence of an effective fluxing amount of a fluxing agent which is a hydrazine monoperfluoro alkanoate containing from 4 to about 20 carbon atoms.

3. A method of soldering metal in which a corrosion-resistant coating is provided, which comprises applying molten solder to the metal in the presence of an effective fluxing amount of a fluxing agent which is a hydrazine monoperfluoro alkanoate containing from 7 to about 16 carbon atoms.

4. A method of soldering copper in which a corrosion-resistant coating is provided, which comprises applying molten solder to copper in the presence of a fluxing agent which is a hydrazine monoperfluoro alkanoate.

5. A method of soldering copper in which a corrosion-resistant coating is provided, which comprises applying molten solder to copper in the presence of a fluxing agent which is a hydrazine monoperfluoro alkanoate containing 4 to about 20 carbon atoms.

6. A method of soldering copper in which a corrosion-resistant coating is provided, which comprises applying

molten solder to copper in the presence of a fluxing agent which is a hydrazine monoperfluoro alkanoate containing from 7 to about 16 carbon atoms.

7. The method of claim 1 wherein the solder contains lead and tin.

8. The method of claim 4 wherein the solder contains lead and tin.

9. A method of applying solder to a metal which comprises applying molten solder to the metal in the presence of hydrazine monoperfluoro octanoate, as the fluxing agent.

10. A method of applying solder to a metal which comprises applying molten solder to the metal in the presence of hydrazine monoperfluoro myristate, as the fluxing agent.

11. A method of applying solder to copper which comprises applying molten solder to copper in the presence of hydrazine monoperfluoro octanoate, as the fluxing agent.

12. A method of applying solder to copper which comprises applying molten solder to copper in the presence of hydrazine monoperfluoro myristate, as the fluxing agent.

References Cited

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